

**Sheraton Yankee Trader Beach Hotel
321 N. Ft. Lauderdale Beach Blvd.
Ft. Lauderdale, Fl 33304
(954) 467-1111**

1.0 Call to Order - Circulate Membership Roster

Meeting called to order at 8:05 am by chairman Mike Lauri

2.0 Committee Organization and Procedures

2.1 Membership Intros were conducted and Roster Circulated.

The attendance was as follows:

NAME	COMPANY
Michael Lauri	IBM
Dave Richardson	Vishay
Len Metzger	Panasonic
Karun Malhotra	Murata Electronics
Phil Diglio	EPCOS
Jack McCullen	Intel
Bill Gisseler	TDK
Mike Cannon	TDK
Barney Martin	NEDA
Hideki Ishida	Sanyo
Kaz Yoshida	Sanyo
Carl Lindquist	San-O Industrial Corp
Jayson Young	Kemet Electronics
Dan Giblin	Cooper Bussmann
Jack Crawford	IPC
Laird Macomber	Cornell Dubilier
Michael Griffith	KOA Speer
Joe Biernacki	Stackpole Electronics
Frank Hayward	American Technical Ceramics
Stephen Olster	Mini-Systems Inc
Ted Coler	Vishay
Dave Ritchey	Yageo Corp
Mary Carter Berrios	Kemet Electronics
Fred Froutan	Rohm
Ed Mikoski	ECA

A quorum was present.

Member Organizations Present	Present at this meeting (Spring 2006)	Present at Fall 2005 Meeting	Present at Spring 2005 Meeting
ATC	Y	N	Y
Cooper Bussmann	Y	Y	Y
Cornell Dubilier	Y	Y	Y
Epcos	Y	Y	Y
IBM	Y	Y	Y
Intel	Y	N	N
Kemet	Y	Y	Y

KOA Speer Electronics	Y	Y	Y
Mini-Systems Inc	Y	N	Y
Murata Electronics	Y	Y	Y
Panasonic	Y	Y	Y
Rohm Electronics	Y	N	N
San-O-Industrial Corp	Y	Y	Y
SEI Electronics	Y	Y	N
TDK	Y	Y	Y
Vishay	Y	Y	Y
Yageo	Y	N	Y

Member Organizations Absent	Present at this meeting? (Spring 2006)	Present at Fall 2005 Meeting	Present at Spring 2005 Meeting
AVX	N	Y	Y

Other Organizations Present
EIA/ECA
IPC
NEDA
Sanyo

2.2 Approval of Agenda and Previous Minutes-Motion for approval passed.

2.3 Correspondence - Mike Griffith has a letter from DFARS regarding metals and alloys. All companies should review this spec. Barney Martin of NEDA said there was an effort to address this with congress. An update should be offered at the next meeting.

2.4 Review of Committees Scope- To provide leadership and direction for passive component standards engineering working groups. The Committee will offer an opportunity for creating a unifying environment for interaction between all passive component users and producers. No changes required at this time.

3.0 Environmental Update and ECA – Ed Mikoski - Ed gave a brief update on the environmental issues facing the industry. The EIA has an Environmental Issues Counsel to address this matter. Also, TC 111 is up and running. The environmental declarations guide EIA-954 is published and is now in revision. The EIA is working closely with the IPC and JEDEC on this new revision.

4.0 Presentations

Hideki Ishida of Sanyo presented on the new JEITA Test Methodology for Low Inductance Capacitors. Mr Ishida is the chairman of the JEITA passive component group. A procedure for ESL measurement was described in the presentation. Proposed document for IEC is 40/1741/NP. There were concerns about specifying a particular vendor (Agilent) for the impedance analyzer. The specification should define only the test jig and procedure and allow the impedance analyzer to be provided from other vendors.

5. Old Business

5.1 PN5115 The Facts about Tin Whiskers CB19A – Completed and published and on ECA Website

5.2 PN5118 Comments on Test Methods & Criteria for Tin Whiskers in Surface Mount Passive Devices – Complete and on ECA Website as CB-22.

5.3 PN 5117 Correction to EIA-481- Complete and on ECA Website as CB-20

5.4 PN 5116 Counterfeit Passive Components - Complete and on ECA Website as CB-21

All four of these CB's have been published and are on the ECA website.

6. New Business

6.1 Status of PN5133 – Environmental Acceptance Requirements For Whisker Susceptibility of Lead-Free Alloy Surface Finishes - Mike Griffith reported (ref JESD 201) on a proposed ECA CB document. Methods for incorporating ECA/Passives inputs to the JEDEC and IPC standards for tin whiskers were discussed. Many typo errors and changes were suggested for this revision. Murata gave comments and information that needs to be discussed in another session and followed up by a conference call. Another call will be setup for the July timeframe.

6.2 Intro to IPC specs Jack Crawford - IPC. Jack Crawford of IPC talked on MSL ratings for components. Topics covered were: Solderability, MSD, Thermal considerations (melting, explosions), Shelf Life etc. He proposed that a joint standard be developed for components that gives reflow thermal and process capability information. This could be similar to MSL but refer to ramp rate, peak temperature, dwell time, etc. All IPC drafts are available at no charge from www.IPC.org/status. Also check answers@IPC.org for general information about IPC.

6.3 Jack McCullen/JEDEC Committee Chairman – Intel, Discussion on interest in combining MSL Specs of JEDEC and IPC to include Passive Components. Date and location for next IPC/JEDEC joint June 23 in Lake Tahoe meeting. ECA is invited to have representation at this meeting.

7. Future Meetings

Fall Engineering Summit – Sept 25-28 2006 in Reno, NV

Spring Engineering Summit – April 2007 – San Diego, CA

8. Action Items – Chairmen to setup another conference call for the July timeframe

9. Adjournment - Meeting was adjourned at 11:10am.